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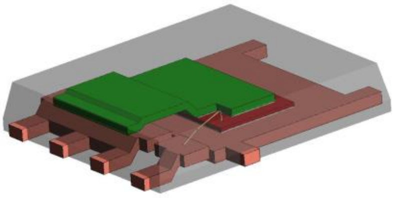
Singapore

UTAC Announces New High Output Copper Clip DFN for Discrete MOSFETs in Ultra High Density (UHD) Leadframes



UTAC Holdings Ltd. (UTAC), a global semiconductor test and assembly services provider, is announcing a punch copper (Cu) clip packaging solution for power MOSFET market.
MOSFETs are key switching devices, used in every power application. To meet demanding thermal, efficiency and size challenges in end applications, performance of these devices needs to continue to evolve – especially for high performance applications such as DC-DC converters in notebook computers, graphics cards and motherboards.

There is significant capacity of MOSFET assembly and test. But UTAC's in-line / modular assembly process provides a very cost effective assembly and test solution.

The copper clip technology not only provides better electrical performance compared with wire bond packages but also provides enhanced thermal path within the package, ensuring that the MOSFET runs cooler, thereby enhancing reliability and enabling greater power densities. The compact MOSFET Cu clip maintains the common package industry footprint of 5 x 6 mm.

Dr. John Nelson, President and CEO, UTAC comments, “Packaging of discrete devices plays a key role in the performance of power solutions. Our new discrete Cu clip line will provide a cost effective solution for our customers.”

He continued “Alongside this we are setting up thin wafer handling (down to 2 mil) for PQFN56 packages and we intend to develop a 10 mil Cu clip for this technology to support further advances.”

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About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of assembly and test services for a broad range of semiconductor chips, and we offer a full range of semiconductor assembly and test services in the following key product categories: analog, mixed-signal and logic, and memory. Our customers are primarily fabless companies, integrated device manufacturers and wafer foundries. UTAC is headquartered in Singapore, with production facilities located in Singapore, Thailand, China, Indonesia and Malaysia, in addition to its global sales network focused on five regions: United States, Japan, China, rest of Asia and Europe, with sales offices located in each of these regions.

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